

# Low Profile SMD Bridge Rectifiers

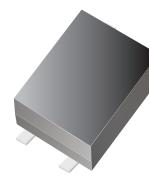
**Comchip**  
SMD Diode Specialist

## CGRHD101-G Thru. CGRHD107-G

Reverse Voltage: 50 to 1000 Volts

Forward Current: 1.0 A

RoHS Device

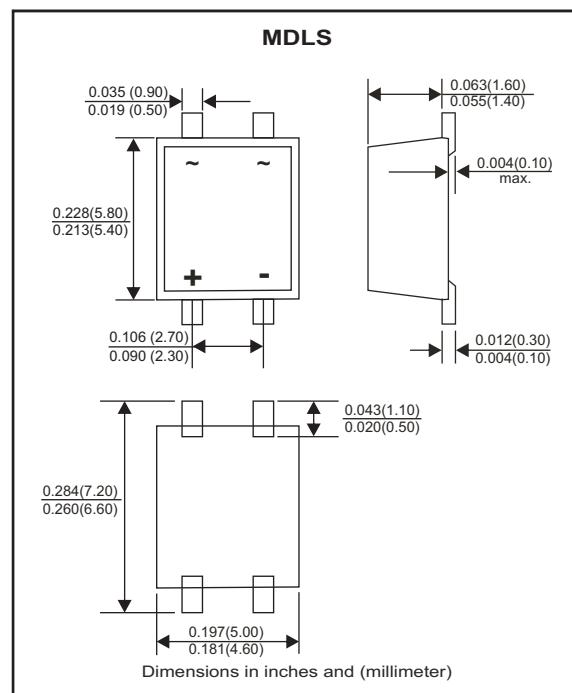


### Features

- Surge overload ratings to 35 amperes peak.
- 1.0A rating in low profile surface mount min-dip bridge save space on printed circuit board.
- Ideal for automated replacement.
- Glass passivated chip junctions.
- UL recognized file # E321971

### Mechanical data

- Epoxy: UL94-V0 rate flame retardant.
- Case: Molded plastic low profile SMD mini-dip(MDLS), Bridge case
- Terminals: solderable per MIL-STD-750,method 2026.
- Polarity: Marking on body.
- Mounting Position: Any
- weight: 0.10 grams (approx.).



### Maximum Rating And Electrical Characteristics

Rating at TA=25°C, unless otherwise noted.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Parameter	Symbol	CGRHD 101-G	CGRHD 102-G	CGRHD 103-G	CGRHD 104-G	CGRHD 105-G	CGRHD 106-G	CGRHD 107-G	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum Continuous Reverse Voltage	V <sub>R</sub>	50	100	200	400	600	800	1000	V
Maximum Forward Rectified Current	I <sub>(AV)</sub>					1.0			A
Peak Forward Surge Current 8.3ms single half sine-wave, superimposed on rate load(JEDEC Method)	I <sub>FSM</sub>					35			A
Maximum Forward Voltage at I <sub>F</sub> =0.5A	V <sub>F</sub>				1.0				V
	V <sub>F</sub>				1.1				
Maximum Reverse Current @V <sub>R</sub> =V <sub>RRM</sub> T <sub>J</sub> =25°C @V <sub>R</sub> =V <sub>RRM</sub> T <sub>J</sub> =100°C	I <sub>R</sub>			5.0					μA
	I <sub>R</sub>			150					
Typical Thermal Resistance Junction to ambient,note 1	R <sub>θJA</sub>			62.5					°C/W
	R <sub>θJL</sub>			25.0					
Typical Junction Capacitance (Per leg, note 2)	C <sub>J</sub>			25					pF
Operating Temperature Range	T <sub>J</sub>			-55 to +150					°C
Storage Temperature Range	T <sub>STG</sub>			-65 to +175					°C

Notes: 1. Thermal resistance from Junction to Ambient and from junctionto lead mounted on glass epoxy P.C.B 0.8\*0.8(20\*20mm) copper pad.  
2. Measure at 1.0 MHz and applied reverse voltage of 4.0 volts.

REV:C

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## RATING AND CHARACTERISTIC CURVES (CGRHD101-G thru CGRHD107-G)

Fig.1 - Forward Current Derating Curve

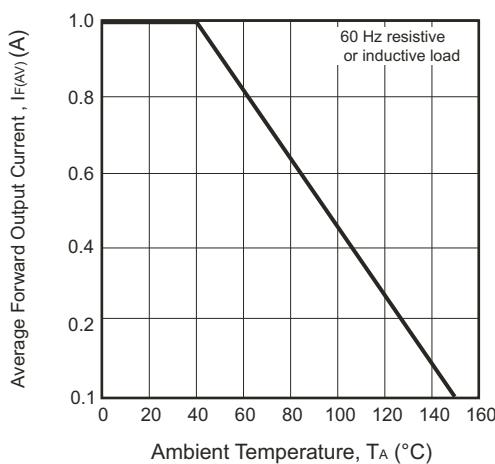


Fig.2 - Maximum Non-Repetitive Peak Forward Surge Current

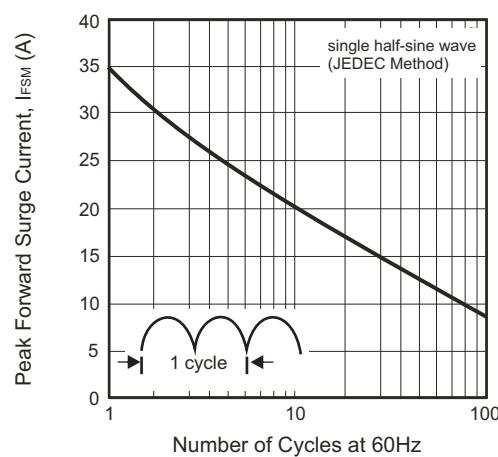


Fig.3 - Typical Instantaneous Forward Characteristics (Per Leg)

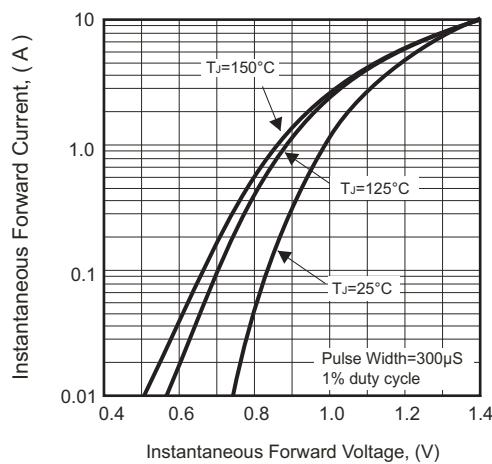


Fig.4 - Typical Reverse Characteristics (Per Leg)

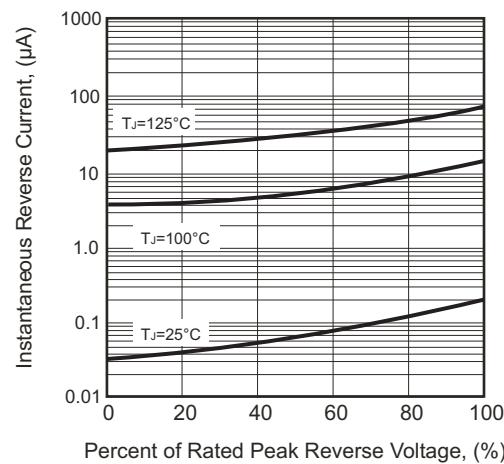
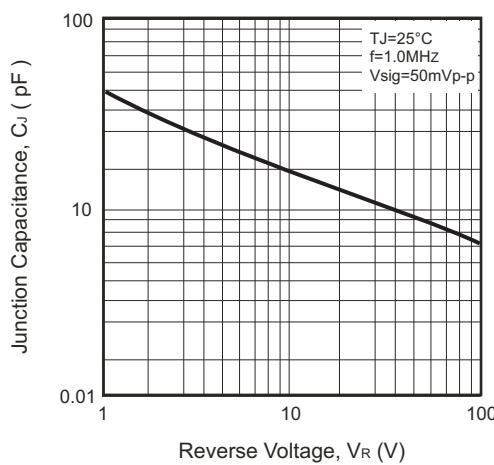
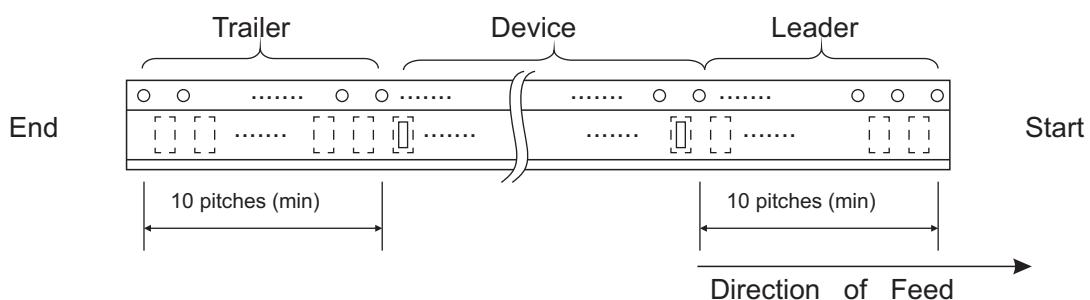
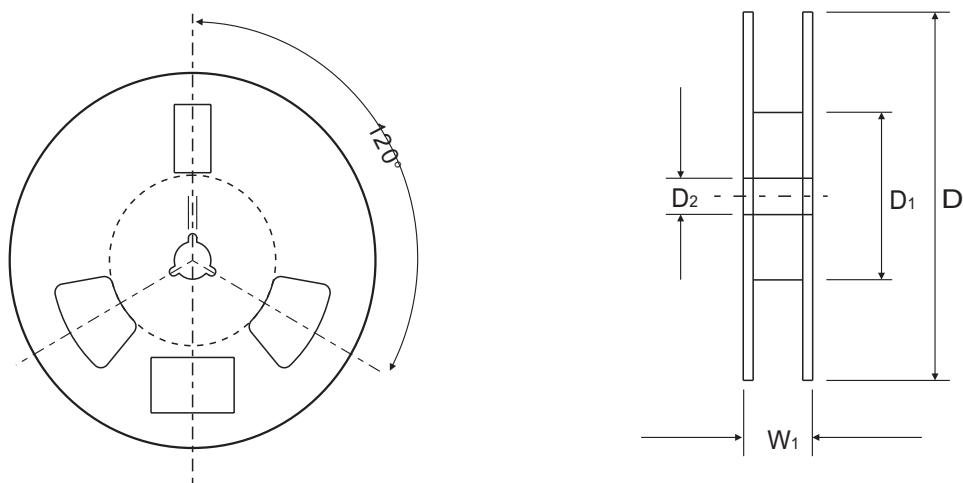
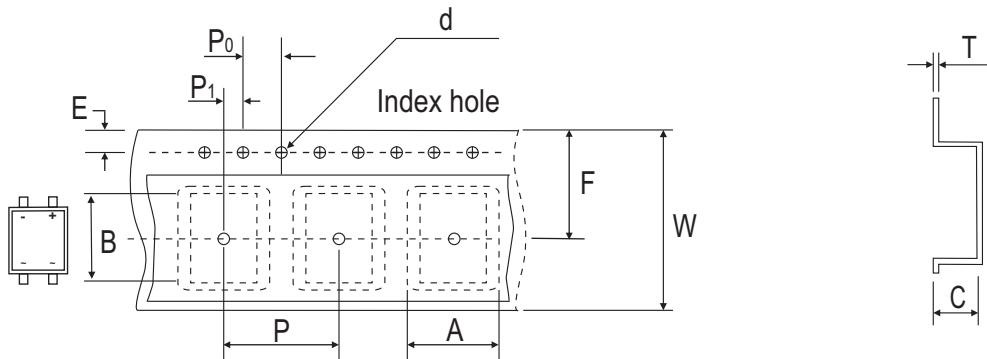


Fig.5 - Typical Junction Capacitance (Per Leg)



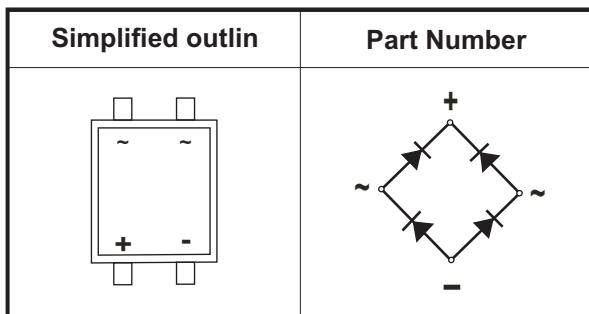
## Reel Taping Specification



MDLS	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	$5.05 \pm 0.10$	$7.01 \pm 0.10$	$1.70 \pm 0.10$	$1.50 \pm 0.05$	$330 \pm 1.50$	$75.00 \pm 1.00$	$13.50 \pm 0.50$
	(inch)	$0.199 \pm 0.004$	$0.276 \pm 0.004$	$0.067 \pm 0.004$	$0.059 \pm 0.002$	$12.99 \pm 0.059$	$2.95 \pm 0.039$	$0.531 \pm 0.020$

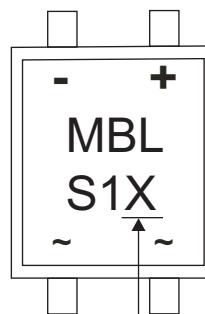
MDLS	SYMBOL	E	F	P	P0	P1	W	W1
	(mm)	$1.75 \pm 0.10$	$5.50 \pm 0.05$	$8.00 \pm 0.10$	$4.00 \pm 0.10$	$2.00 \pm 0.25$	$12.0 \pm 0.15$	$13.5 \pm 0.50$
	(inch)	$0.069 \pm 0.004$	$0.217 \pm 0.002$	$0.315 \pm 0.004$	$0.157 \pm 0.004$	$0.079 \pm 0.010$	$0.472 \pm 0.006$	$0.531 \pm 0.020$

## Pinning information



## Marking Code

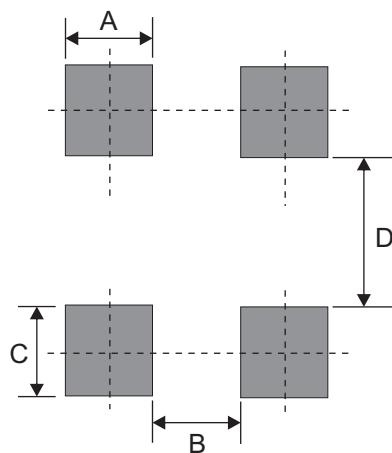
Part Number	Marking code
CGRHD101-G	MBLS1A
CGRHD102-G	MBLS1B
CGRHD103-G	MBLS1D
CGRHD104-G	MBLS1G
CGRHD105-G	MBLS1J
CGRHD106-G	MBLS1K
CGRHD107-G	MBLS1M



X = Product type marking code

## Suggested PAD Layout

SIZE	MDLS	
	(mm)	(inch)
A	1.50	0.059
B	1.20	0.047
C	1.20	0.047
D	5.40	0.213



## Standard Packaging

Case Type	Reel	
	Qty Per Reel	Reel Size
	(Pcs)	(inch)
MDLS	5,000	13